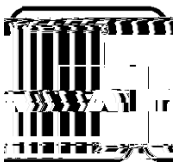
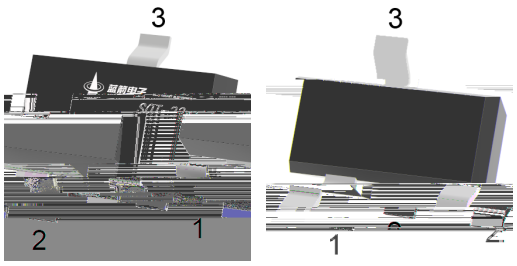
SOT-23 Silicon Diode in a SOT-23 Plastic Package.

AEC-Q101

Small signal diode, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

High Conductance Ultra Fast Diode, Meet the stringent requirements of automotive applications.



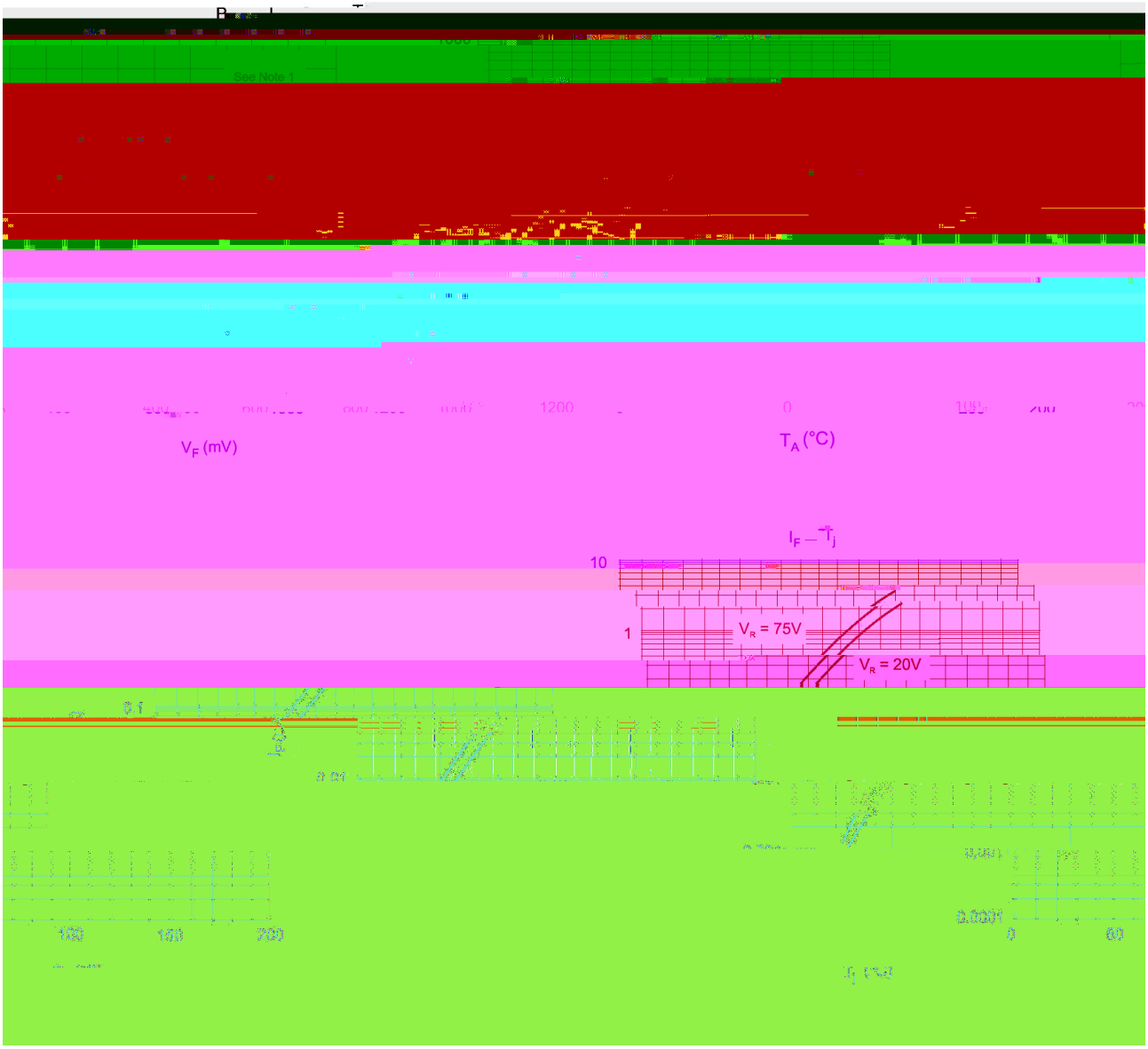


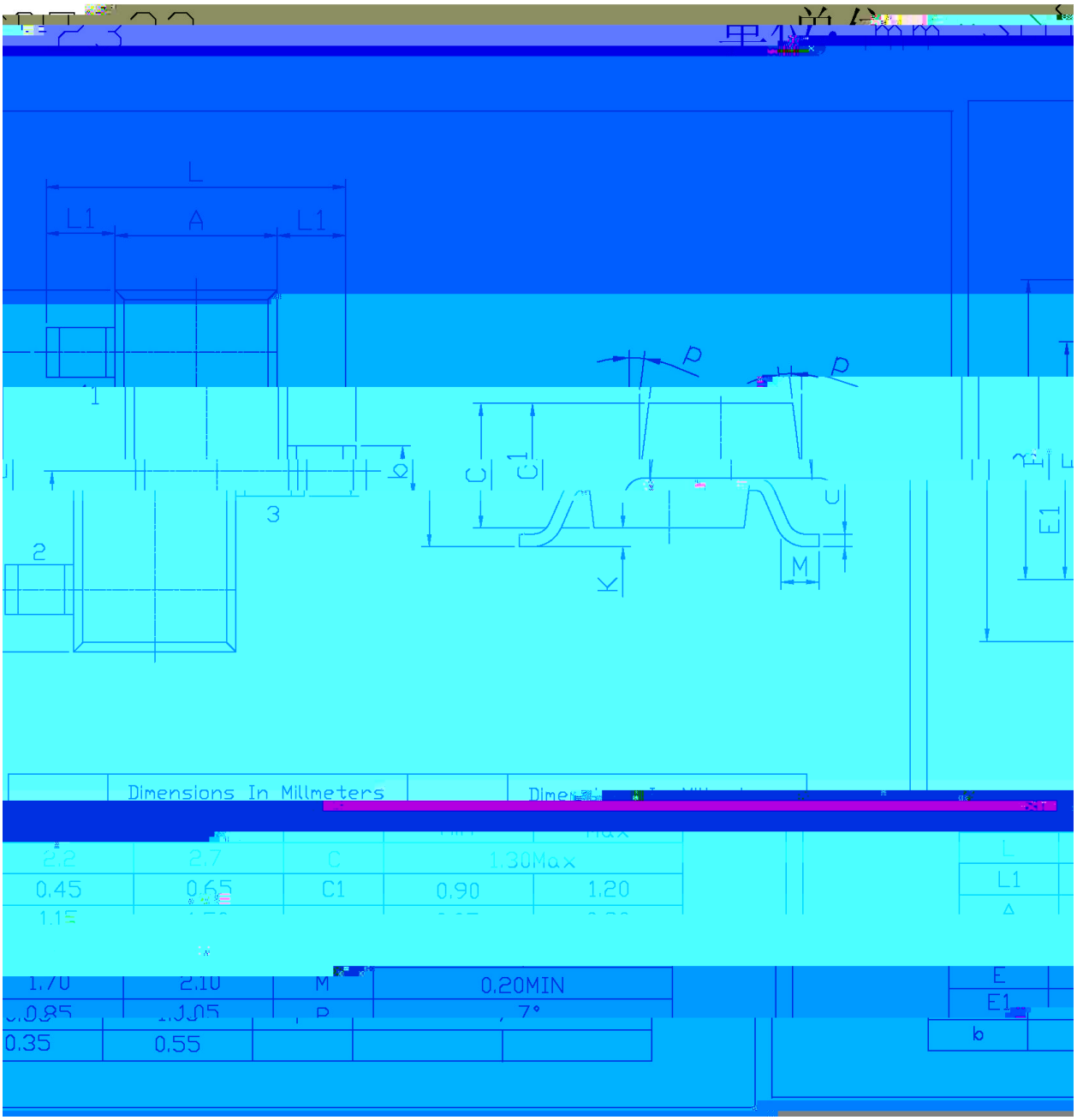
PIN: See Equivalent Circuit.

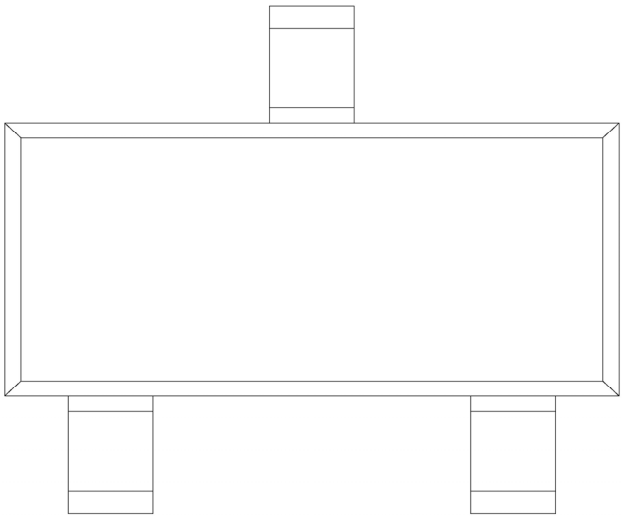
Marking	QA4

Parameter	Symbol	Rating	Unit
Maximum Repetitive Reverse Voltage	V_{RRM}	75	V
Breakdown Voltage	V_R	70	V
Average Rectified Forward Current	$I_{F(AV)}$	200	mA
Non-repetitive Peak Forward Surge Current	$I_{FSM(1)(pulse\ width=1.0S)}$	1.0	A
	$I_{FSM(2)(pulse\ width=1.0mS)}$	2.0	A
Power Dissipation	P_D	350	mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	357	/W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Breakdown Voltage	V_R	I_R=100μA	70			V
Forward Voltage	V_F	I_F=1.0mA			715	mV
		I_F=10mA			855	mV


See Note 1
V_F (mV)
T_A (°C)
$I_F - T_j$
10
1
V_R = 75V
V_R = 20V
0.1
0.01
0
60
T_j (°C)

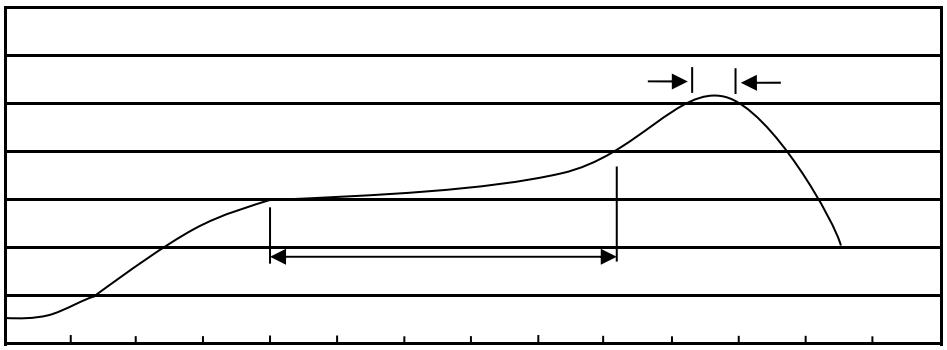

L
L1
A
L1
C
C1
M
E1
Dimensions In Millmeters
2.2
2.7
C
1.30Max
0.45
0.65
C1
0.90
1.20
L
L1
1.70
2.10
M
0.20MIN
E
E1
0.35
0.55
b



Q

A4

Temperature Profile for IR Reflow Soldering(Pb-Free)



		Note:	
1	150 200 60 120sec;	1.Preheating:150~200 , Time:60~120sec.	
2	255±5 5±0.5sec;	2.Peak Temp.:255±5 , Duration:5±0.5sec.	
3	2 10 /sec.	3.Cooling Speed: 2~10 /sec.	

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ REEL

Package Type	Units					Dimension		(unit mm³)
SOT-23	3,000	10	30,000	6	180000	7 ×8	180×120×180	390×385×205